**ONE-STOP SUPPLIER OF SEMICONDUCTOR CARRIER PRODUCTS** 

# Hiner-pack® SHWS-PP Carrier 100 mm

Provides secure single wafer protection with clear visibility for easy inspection

Engineered for maximum protection and inspection convenience, coin-style single wafer shippers are a trusted solution in semiconductor wafer packaging. Molded from transparent natural polypropylene, they enable easy wafer inspection without exposing the wafer to air or contaminants. This clear design safeguards wafer quality during shipping and storage, minimizing handling damage. Suitable for the entire wafer journey—from fabrication facilities to assembly lines—they are offered in 4" and 6" sizes, with customization available for unique requirements. Coin-style shippers combine durability, contamination control, and visual verification in one compact wafer transport solution.



### **SPECIFICATIONS**

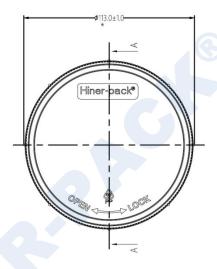
- Φ 113 mm × 15.9 mm H ( 4.45" × 0.626")
- Maximum load capacity is 1 piece

## **FEATURES & BENEFITS**

- Conical pocket holds one wafer facedown contacting only the wafer's edge
- Spring retains wafer and minimizes particle generation
- Stackable for efficient use of storage space
- · Screw on cover provides secure closure and easy opening
- The enclosed structure minimizes exposure to contaminants
- Large area on cover provides space for labeling



## **DIMENSION**





# **BASIC INFORMATION**

Part Number	Collocation Reference	Wafer Size
SHWS-4/1-NP	Bottom+Spring+Top	100 mm

# **REFERENCE ILLUSTRATION**



The above illustration is for reference only. Please refer to the actual product for accuracy.

### **TECHNICAL DATA**

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183	0.9 g/cm <sup>3</sup>
Melt Index	ISO 1133	15 g/10min
Melting Point	DSC	146°C
Distortion Temperature	ISO 75	95°C
Vicat softening temperature	ISO 306	125°C
Tensile Strength at Yield	ISO 527	280 kg/m²
Tensile Elongation at Break	ISO 527	300 %
Rockwell hardness R scale	ISO 2039	98
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Modulus	ISO 178	10500 kg/m <sup>2</sup>
Flow Shrinkage	FPC Method	1.3~1.7 %
LZOD Impact Strength	23°C ISO 180	6 kg.cm/cm
LZOD Impact Strength		6 kg.cm/cm notch

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.



## **Corporate Headquarters**

Bldg A11, Zone D, West Industrial Zone, Minzhu Comm., Shajing St., Bao'an, Shenzhen, Guangdong, China

### **Customer Service**

Tel +86 755 2322 9236 Fax +86 755 2996 0455

Work Time 08:00 - 18:00 (Beijing Time/UTC+8)

 $\label{eq:hiner-pack} \mbox{Hiner-pack$^{\otimes}$ is a registered trademark of Shenzhen Hiner Technology Co., Ltd.}$ 

©2013-2025 Shenzhen Hiner Technology Co., Ltd. | All rights reserved.